



## Tpreg™ HTD Circuit Boards Materials

Tpreg™ HTD is a thermally conductive dielectric adhesive pre-preg material.

Tpreg™ HTD is used in conjunction with copper foil and an integral metal plate to provide a circuit board laminate that has superior thermal management capabilities and a 150°C continuous use temperature.

Item #	Max. Continuous Operating Voltage	Thermal Conductivity	Thermal Resistance	Dielectric Thickness	Peel Strength
HTD04	240 VAC 450 VDC	2.20 W/m-K	0.072 °C-in <sup>2</sup> /W 0.464 °C-cm <sup>2</sup> /W	0.004 inches 0.102 mm	6.5 lb/in 1.16 kg/cm
HTD06	480 VAC 950 VDC	2.20 W/m-K	0.107 °C-in <sup>2</sup> /W 0.690 °C-cm <sup>2</sup> /W	0.006 inches 0.152 mm	7.0 lb/in 1.25 kg/cm